

AQUEOUS DISPERSING ELEMENT FOR POLISHING CHEMICAL MACHINE

Patent number: JP2001269859
Publication date: 2001-10-02
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Classification:
- **International:** B24B37/00; C09K3/14; H01L21/304; H01L21/306
- **European:**
Application number: JP20000087015 20000327
Priority number(s):

Also published as:

EP1138733 (A2)
US2001049912 (A1)
EP1138733 (A3)

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Abstract of JP2001269859

PROBLEM TO BE SOLVED: To provide an aqueous dispersing element for polishing a chemical machine capable of suppressing the occurrence of scratches even on an interlayer insulating membrane having a small elastic modulus.

SOLUTION: This aqueous dispersing element for polishing a chemical machine can suppress the occurrence of scratches of a specific size to a specific number or below even on a soft interlayer insulating membrane having the elastic modulus measured by the nano-indentation method at 20 Gpa or below, particularly 10 Gpa or below, and further 5 Gpa or below. This aqueous dispersing element uses organic inorganic composite grains or the like for abrasive grains, and it can be prepared by blending at least one kind of scratch inhibitor selected from a heterocyclic compound such as 7-hydroxy-5-methyl-1,3,4- triazindolizine of 0.01-5 mass %, particularly 0.05-2 mass %, and a nonionic surface active agent such as polyoxyethylene alkylether of 0.0001-0.1 mass %, particularly 0.0005-0.05 mass %, with it.

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